

# COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## SEMICONDUCTOR PACKAGING SUBSTRATE AND METHOD OF PRODUCING THE SAME

the specification of which

is attached hereto.

was filed on \_\_\_\_\_

as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

| Number   | Country        | Date Filed(yyyy/mm/dd) | Yes | No |
|----------|----------------|------------------------|-----|----|
| 90132738 | Taiwan, R.O.C. | 2001/12/28             | X   |    |

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

|                        |                   |                 |                   |
|------------------------|-------------------|-----------------|-------------------|
| Jiawei Huang           | (Reg. No. 43,330) | Charles C.H. Wu | (Reg. No. 39,081) |
| Maria Erlinda C. Sarno | (Reg. No. 37,436) | Marrina Mei     | (Reg. No. 44,935) |
| Belinda Lee            | (Reg. No. 46,863) |                 |                   |

---

SEND CORRESPONDENCE TO:

DIRECT TELEPHONE CALLS TO:

(Name and telephone number)

J.C. Patents, Inc.  
4 Venture, Suite 250  
Irvine, CA 92618  
(949) 660-0761

Jiawei Huang  
(949) 660-0762

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: Chi-Hsing Hsu Date: Jan. 22, 2002

Sole or First Joint Inventor: Chi-Hsing Hsu

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: 9F-1, No. 23, Changlung St., Hsinchuang, Taipei Hsien, Taiwan, R.O.C.

Signature: Wen-Yuan Chang Date: Jan. 22, 2002

Second Joint Inventor (if any): Wen-Yuan Chang

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: 8F., No. 533, Chung-Cheng Rd., Hsinchu, Taiwan, R.O.C.